Infratron Kool Pad Chip Pad KA150

KA150-2AC	Material	Thermal Impedance °C/W (Area:TO3)	Adhesive Strength N/cm	Temperature Range
Property	Aluminium Foil	0.49	5.5	-20°C to +155°C
Test Method	-	ASTM D5470	-	-

Description

KOOL-PADS KA150-2AC material is designed to provide an efficient method of mounting heatsinks onto devices such as microprocessors, small electronic packages and other components which require heatsinks.

Kool-Pads KA150-2AC makes a fast and efficient thermal interface and eliminates the need for clips, clamps or any other form of mechanical fixing. The use of messy thermal compound is also eliminated. Kool-Pads KA150-2AC incorporates a highly conductive aluminium foil which is coated both sides with thermally-conductive high-strength adhesive.

Ordering information

Standard sheet sizes are 300mm x 300mm each.

KA150-2AC-30x30

An extensive range of pre-cut profiles is also available, see additional datasheet for details.

Key performance Properties

- High strength bonding means no further fixing clip is required to secure component and heatsink together.
- Provided with back and front polypropylene interliner
- Remains resistant to cleaning agents , and does not support organic growth
- Adhesive strength increases 4 fold over initial 48 hours .No known deterioration over time.
- Easily cut at room temperature into most configurations using steel rule dies or sharp blades.
- Low tooling costs for custom profiles

Technical Information	Property	Test Standard
Part prefix code	KA150-2AC	
Thickness (mm)	0.16 ±0.02	
Interliner	Polypropylene	
Thermal resistance **per cm²**	2.90°C/W	
Hardness	90 ±5	Shore Micro
Tear Resistance kN/m	48	ASTM D624
Tensile Strength MPa	22	ASTM D412
Dielectric Constant 1000Hz	2.6	ASTM D150
Elongation %	8	ASTM D412
Colour	Cream	
Temperature range	-20°C to 155°C	
Datasheet Issue	04	

For further information on this or any other thermal material call our help line on ++49-(0)89-15 81 26-0 and visit our website at www.Infratron.de

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